

In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 245°C FOR INSERTION DURATION, 5 sec.	SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	X	-
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING «REFLOW AREA» MAX250°C WITHIN 10 sec MIN 220°C WITHIN 60 sec «PREHEATING AREA» 150~180°C 90~120s 2) MANUAL SOLDERING SOLDERING IPON TEMPERATURE 350±10°C SOLDERING TIME 3~4s. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	-

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REMARKS

NOTE 1: INCLUDING THE TEMPERATURE RISE BY CURRENT.
 NOTE 2: NON-CONDENSING
 NOTE 3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD.
 AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION

Unless otherwise specified , refer to JIS C 5402.

Note QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.	ELG4-330237-02	
HRS	SPECIFICATION SHEET	PART NO.	DF50-50DP-1V(52)	
	HIROSE ELECTRIC CO., LTD.	CODE NO	GL665-0011-1-52	△